

**Amendments to the Claims:**

38. (Currently Amended) A semiconductor package comprising:

a plurality of leads each defining opposed first and second sides and an inner end, the leads being arranged such that the inner ends collectively define a central region;

a first semiconductor chip disposed in the central region and having a plurality of input/output pads;

a second semiconductor chip having a plurality of central input/output pads and a plurality of peripheral input/output pads, each of the central input/output pads ~~superimposing and~~ being aligned with and electrically connected to a respective one of the input/output pads of the first semiconductor chip, with each of the peripheral input/output pads ~~superimposing and~~ being aligned with and electrically connected to the first side of a respective one of the leads; and

a package body at least partially encapsulating the leads and the first and second semiconductor chips such that at least a portion of the second side of each of the leads is exposed in an exterior surface of the package body.